



## FEATURES

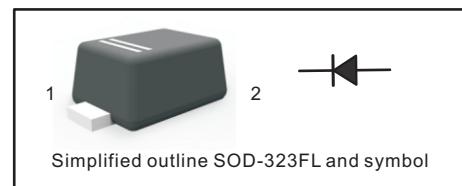
- For surface mounted applications
- Glass Passivated Chip Junction
- Fast reverse recovery time
- Ideal for automated placement
- Lead free in comply with EU RoHS 2011/65/EU directives

## MECHANICAL DATA

- Case: SOD-323FL
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 4.5mg / 0.00016oz

## PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



## Absolute Maximum Ratings at 25 °C

Parameter	Symbols	T-1N4148WSL			Units
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	100			V
Maximum RMS voltage	$V_{RMS}$	75			V
Average Rectified Forward Current	$I_{F(AV)}$	150			mA
Non-repetitive Peak Forward Surge Current	$I_{FSM}$	0.5 1 4			A
Total Power Dissipation	$P_{tot}$	400			mW
Operating and Storage Temperature Range	$T_j, T_{stg}$	-55 ~ +150			°C

## Characteristics at $T_a = 25^\circ\text{C}$

Parameter	Symbols	T-1N4148WSL			Units
Reverse Breakdown Voltage at $I_R=1\mu\text{A}$	$V_{(BR)R}$	75			V
Maximum Forward Voltage	$V_F$	0.715 0.855 1.00 1.25			V
Peak Reverse Current	$I_R$	0.025 1 30 50			$\mu\text{A}$
Typical Junction Capacitance $f=1\text{MHz}, V_R=0\text{V}$	$C_j$	2			pF
Maximum Reverse Recovery Time <sup>(1)</sup>	$t_{rr}$	4			ns

(1) Measured with  $I_F=I_R=10\text{mA}, I_{rr}=0.1\times I_R, R_L=100\Omega$



Fig.1 Power Derating Curve

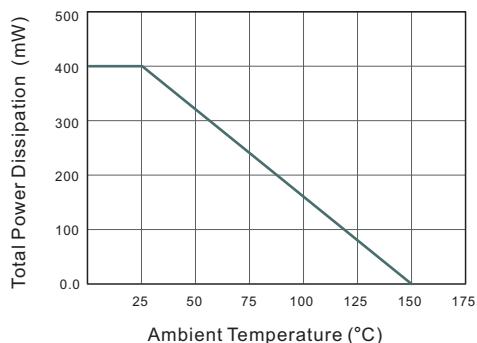


Fig.2 Typical Reverse Characteristics

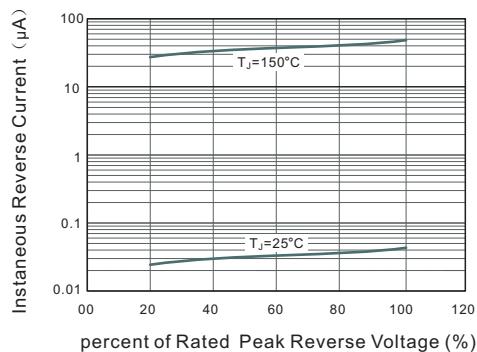


Fig.3 Typical Instaneous Forward Characteristics

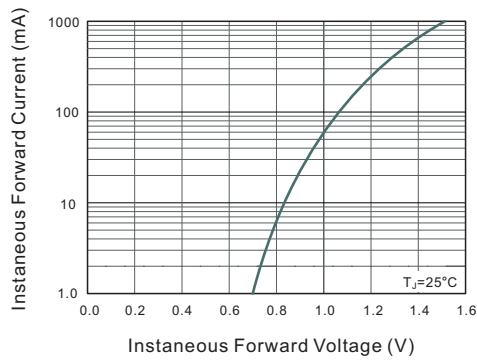
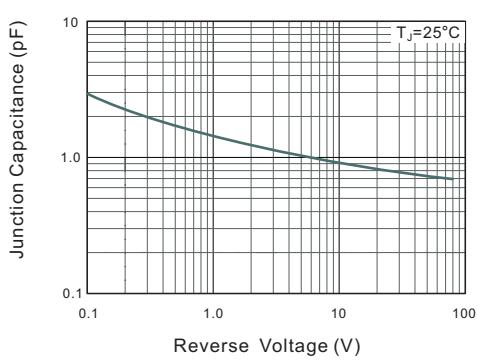


Fig.4 Typical Junction Capacitance

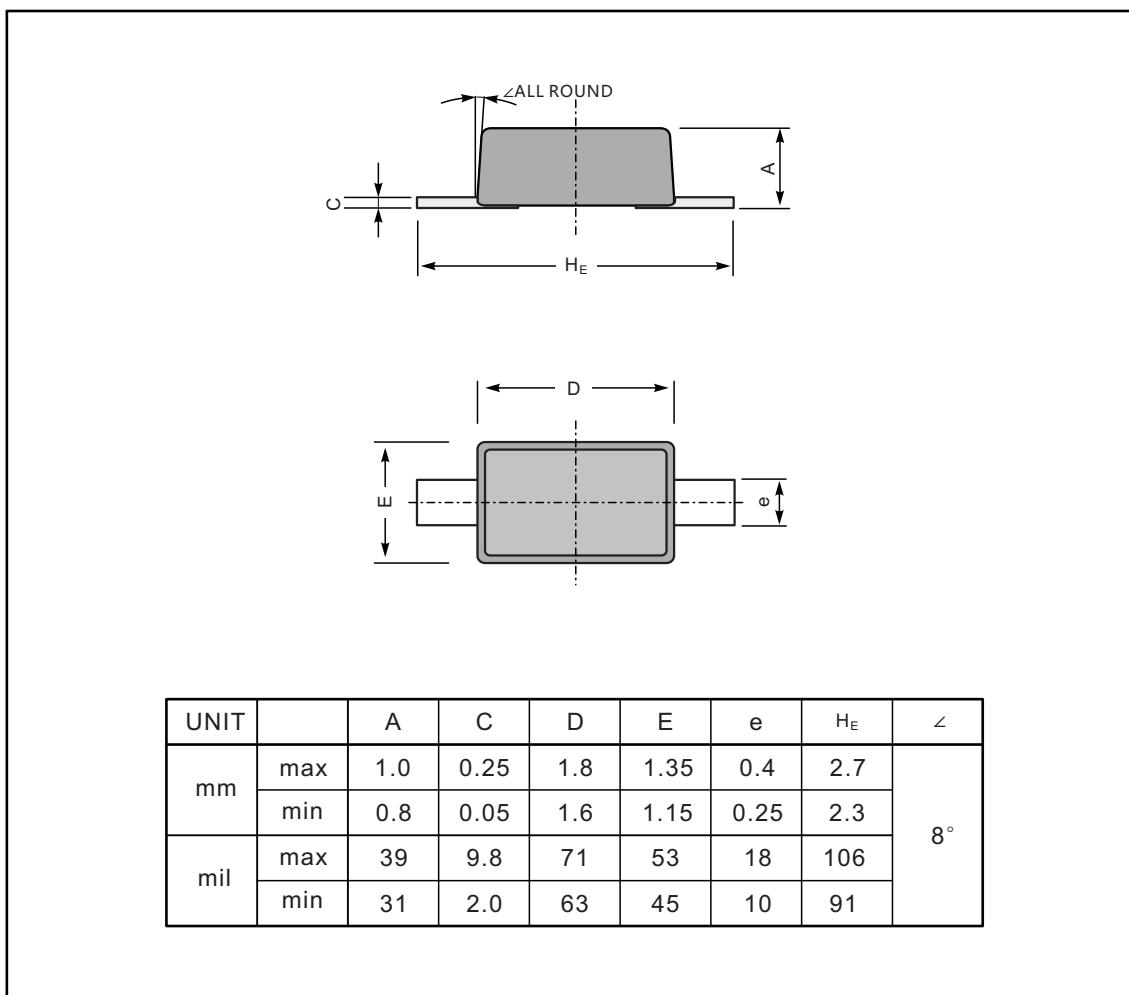




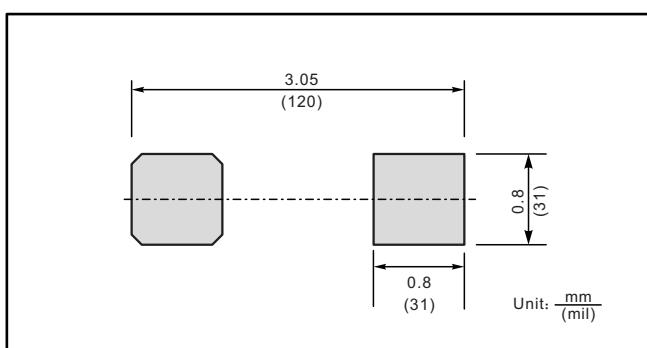
## PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SOD-323FL



### The recommended mounting pad size



### Marking

Type number	Marking code
T-1N4148WSL	T4